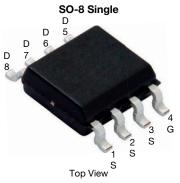


Vishay Siliconix

Automotive N-Channel 60 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	60				
$R_{DS(on)} (\Omega)$ at $V_{GS} = 10 V$	0.022				
$R_{DS(on)} (\Omega)$ at $V_{GS} = 4.5 V$	0.031				
I _D (A)	12				
Configuration	Single				
Package	SO-8				



FEATURES

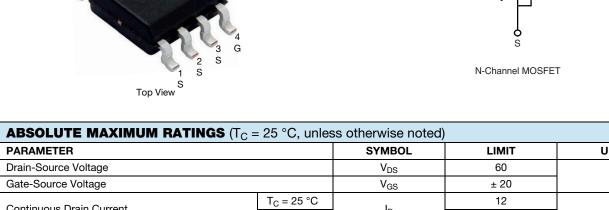
- TrenchFET[®] power MOSFET
- 100 % Rg and UIS tested
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

G

D



COMPLIANT HALOGEN FREE



PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V _{DS}	60	V	
Gate-Source Voltage		V _{GS}	± 20	V	
Continuous Drain Current	T _C = 25 °C	- I _D	12		
Continuous Drain Current	T _C = 125 °C		6.9		
Continuous Source Current (Diode Conduction	I _S	6.2	А		
Pulsed Drain Current ^a		I _{DM}		48	
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	23		
Single Pulse Avalanche Energy	L = 0.1 IIIH	E _{AS}	26	mJ	
Maximum Power Dissipation ^a	T _C = 25 °C	PD	6.8	W	
	T _C = 125 °C		2.2		
Operating Junction and Storage Temperature F	Range	T _J , T _{stg}	-55 to +175	°C	

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	LIMIT	UNIT		
Junction-to-Ambient	PCB Mount ^b	R _{thJA}	85	°C/W		
Junction-to-Foot (Drain)		R _{thJF}	22	0/10		

Notes

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

b. When mounted on 1" square PCB (FR4 material).

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SQ4850EY

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$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	MAX. U	TYP.	MIN.	TEST CONDITIONS		SYMBOL	PARAMETER		
$ \begin{array}{c c c c c c c } \hline Gate-Source Inreshold Voltage & V_{GS(th)} & V_{DS} = V_{GS}, I_D = 250 \ \mu A & 1.5 & 2 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0$. <u> </u>			•	Static		
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	-	-	60	V _{GS} = 0, I _D = 250 μA		V _{DS}	Drain-Source Breakdown Voltage		
$ \begin{array}{c c c c c c c } \hline Gate-Source Leakage & I_{GSS} & V_{DS} = 0 \lor, V_{GS} = \pm 20 \lor & & & & & & & &$	2.5	2	1.5	: V _{GS} , I _D = 250 μΑ	V _{DS} =		Gate-Source Threshold Voltage		
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	± 100	-	-	0 V, V_{GS} = ± 20 V	V _{DS} =		Gate-Source Leakage		
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	1.0	-	-	V _{DS} = 60 V	$V_{GS} = 0 V$				
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	50	-	-	V _{DS} = 60 V, T _J = 125 °C	$V_{GS} = 0 V$	I _{DSS}	Zero Gate Voltage Drain Current		
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	150	-	-	V _{DS} = 60 V, T _J = 175 °C	$V_{GS} = 0 V$				
$ \begin{tabular}{ c c c c c } \hline Prime \begin{tabular}{ c c c c c } \hline Prime \begin{tabular}{ c c c c c } \hline Prime \begin{tabular}{ c c c c c c c } \hline Prime \begin{tabular}{ c c c c c c c c c c c c c c c c c c c$	-	-	30	$V_{DS} \ge 5 V$	V _{GS} = 10 V	I _{D(on)}	On-State Drain Current ^a		
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	0.022	0.017	-	I _D = 6 A	$V_{GS} = 10 V$				
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	0.037	0.029	-	I _D = 6 A, T _J = 125 °C	V _{GS} = 10 V		Durin Course On Chate Desistence &		
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	0.047	0.037	-	I _D = 6 A, T _J = 175 °C	V _{GS} = 10 V	R _{DS(on)}	Drain-Source On-State Resistance ª		
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	0.031	0.025	-	I _D = 5 A	V _{GS} = 4.5 V				
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	-	21	-	= 15 V, I _D = 6 A	V _{DS}		Forward Transconductance b		
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $					•	•	Dynamic ^b		
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	1250	1000	-	V V _{DS} = 25 V, f = 1 MHz		C _{iss}	Input Capacitance		
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	235	185	-		$V_{GS} = 0 V$	Coss	Output Capacitance		
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	95	75	-				Reverse Transfer Capacitance		
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	30	20	-			Qg	Total Gate Charge ^c		
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	-	2.9	-	$V_{DS} = 30 \text{ V}, \text{ I}_{D} = 6 \text{ A}$	$V_{GS} = 10 V$	Q _{gs}	Gate-Source Charge ^c		
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	-	4.4	-				Gate-Drain Charge ^c		
$ \begin{array}{c c} \hline Rise Time \ ^{\circ} & t_r \\ \hline Turn-Off \ Delay \ Time \ ^{\circ} & t_{d(off)} \\ \hline Fall \ Time \ ^{\circ} & t_f \\ \hline \end{array} \\ \hline \begin{array}{c c} V_{DD} = 30 \ V, \ R_L = 30 \ \Omega \\ I_D \cong 1 \ A, \ V_{GEN} = 10 \ V, \ R_g = 1 \ \Omega \\ \hline - & 23 \\ \hline - & 9 \\ \hline \end{array} \\ \hline \begin{array}{c c} Source-Drain \ Diode \ Ratings \ and \ Characteristics \ ^{b} \\ \hline \end{array} $	2.1	-	0.3	f = 1 MHz			Gate Resistance		
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	11	7	-			t _{d(on)}	Turn-On Delay Time ^c		
Fall Time ° tf Source-Drain Diode Ratings and Characteristics ^b	14	9	-	DD in , L in ,			Rise Time ^c		
Fall Time ° t _f - 9 Source-Drain Diode Ratings and Characteristics ^b	35	23	-			t _{d(off)}	Turn-Off Delay Time ^c		
	14	9	-				Fall Time ^c		
	Source-Drain Diode Ratings and Characteristics ^b								
Pulsed Current ^a I _{SM}	48	-	-			I _{SM}	Pulsed Current ^a		
Forward Voltage V_{SD} $I_F = 1.7 \text{ A}, V_{GS} = 0$ - 0.8	1.2	0.8	-	I _F = 1.7 A, V _{GS} = 0		V _{SD}	Forward Voltage		

Notes

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

2

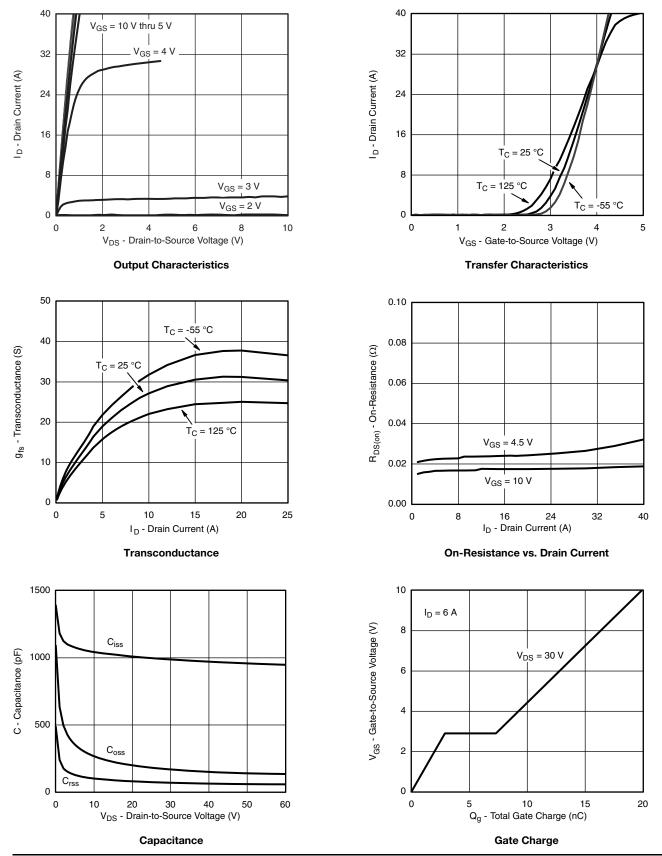
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ISHAY

SQ4850EY

Vishay Siliconix

TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)



S15-1878-Rev. F, 17-Aug-15

3

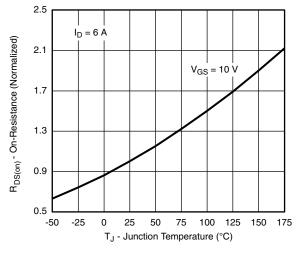
Document Number: 68878

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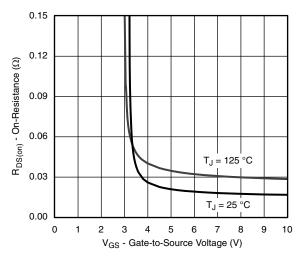


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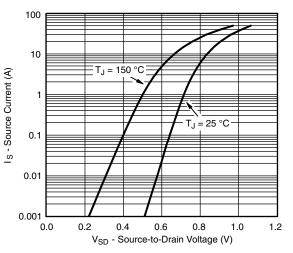
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



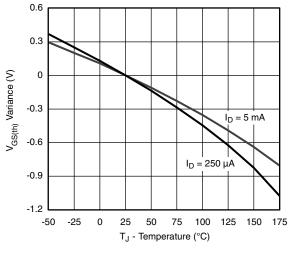
On-Resistance vs. Junction Temperature



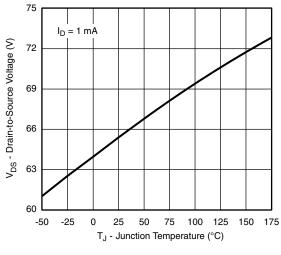
On-Resistance vs. Gate-to-Source Voltage



Source Drain Diode Forward Voltage







Drain Source Breakdown vs. Junction Temperature 4

S15-1878-Rev. F, 17-Aug-15

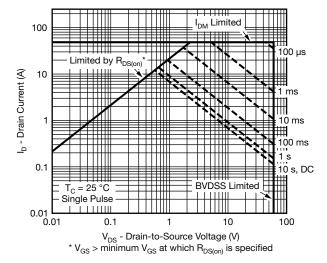
Document Number: 68878

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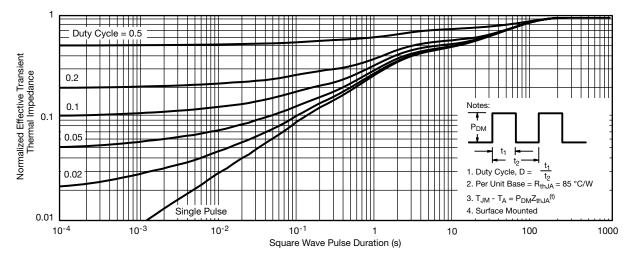


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THERMAL RATINGS ($T_A = 25 \text{ °C}$, unless otherwise noted)



Safe Operating Area

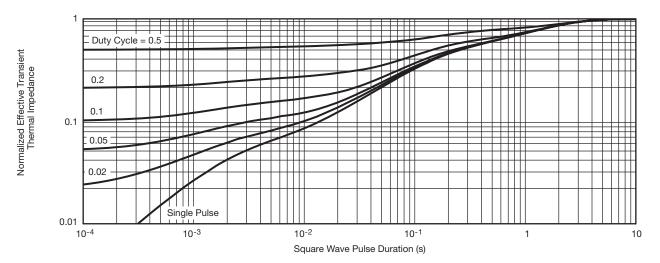


Normalized Thermal Transient Impedance, Junction-to-Ambient



Vishay Siliconix

THERMAL RATINGS ($T_A = 25 \text{ °C}$, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Foot

Note

• The characteristics shown in the two graphs

- Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)

- Normalized Transient Thermal Impedance Junction-to-Foot (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?68878.



Vishay Siliconix

REVISION	HISTORY ^a	
REVISION	DATE	DESCRIPTION OF CHANGE
F	04-Aug-15	Revised R _g minimum limit

Note

a. As of April 2014



Package Information

Vishay Siliconix

SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012





	MILLIM	IETERS	INC	HES	
DIM	Min	Мах	Min	Max	
A	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050 BSC		
н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498					

Application Note 826

Vishay Siliconix



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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